

### **Claim Amendments**

Claims 1-9 (cancelled).

10. (new) A method of fabricating a leadframe structure comprising a chip mount pad and a plurality of lead segments, each of said lead segments having a first end near said mount pad and a second end remote from said mount pad, comprising the steps of:

- plating a layer of nickel on said chip mount pad and said first and second ends of said lead segments;

- selectively plating a layer of palladium on said nickel-plated chip mount pad and first segment ends; and

- selectively plating a layer of tin onto said nickel-plated second segment ends.

11. (new) The method according to Claim 1 wherein said step of selectively plating said palladium is performed through apertures in a wheel.

12. (new) The method according to Claim 1 wherein said plating of said tin layer is performed with photo-imagible masks.

13. (new) The method according to Claim 12 wherein said step of plating said tin layer comprising the steps of:

- coating with a plating resist;

- photoimaging;

- developing said resist;

- plating with tin;

- stripping said resist;

- rinsing; and

- drying.

14. The method of Claim 10 wherein said plating steps are performed using electrolytic plating.